

ABSTRACT OF THE INVENTION

A wire bonding method comprises: a step of preparing a wire bonding apparatus 1; a ball forming step of forming a free air ball (43); a first height measuring step of measuring the height of a first electrode by detecting whether the free air ball (43) is grounded to the first
5 electrode; a second height measuring step of measuring the height of a second electrode by detecting whether the free air ball (43) is grounded to the second electrode; a first bonding step of controlling the height of a bonding tool (40) on the basis of the result of measurement in the first height measuring step, and bonding the free air ball (43) to the first electrode; and a second
10 bonding step of controlling the height of the bonding tool (40) on the basis of the result of measurement in the second height measuring step, and bonding a wire (42) to the second electrode to connect the first electrode and the second electrode. In this way, a plurality of electrodes can be accurately bonded.

FIGURE 1